**Product data sheet** 

## 1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in a medium power DFN2020MD-6 (SOT1220) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

### 2. Features and benefits

- Extended temperature range T<sub>i</sub> = 175 °C
- Side wettable flanks for optical solder inspection
- ElectroStatic Discharge (ESD) protection > 1 kV HBM (class H1C)
- Trench MOSFET technology
- AEC-Q101 qualified

## 3. Applications

- · DC to DC conversion
- High-speed line driver
- · High-side load switch
- Switching circuits

## 4. Quick reference data

#### Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$V_{DS}$	drain-source voltage	T <sub>j</sub> = 25 °C		-	-	-20	V
$V_{GS}$	gate-source voltage			-12	-	12	V
I <sub>D</sub>	drain current	V <sub>GS</sub> = -4.5 V; T <sub>sp</sub> = 25 °C		-	-	-18	Α
P <sub>tot</sub>	total power dissipation	T <sub>sp</sub> = 25 °C		-	-	19	W
Static chara	cteristics		'				'
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS} = -4.5 \text{ V}; I_D = -6 \text{ A}; T_j = 25 \text{ °C}$		-	30	38	mΩ



**BUK4D38-20P** 

# 5. Pinning information

#### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	D	drain	15756	D '
2	D	drain		
3	G	gate	2 5	$_{\rm G}$ $\downarrow$ $\downarrow$ $\downarrow$
4	S	source	3 8 4	<b>│</b>
5	D	drain	Transparent top view	
6	D	drain	DFN2020MD-6 (SOT1220)	S
7	D	drain		017aaa259
8	S	source		

# 6. Ordering information

### **Table 3. Ordering information**

Type number	per Package						
	Name	Description	Version				
BUK4D38-20P		plastic, leadless thermal enhanced ultra thin small outline package with side-wettable flanks (SWF); 6 terminals; 0.65 mm pitch; 2 mm x 2 mm x 0.65 mm body	SOT1220				

# 7. Marking

### Table 4. Marking codes

Type number	Marking code
BUK4D38-20P	6F

# 8. Limiting values

#### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DS}$	drain-source voltage	T <sub>j</sub> = 25 °C		-	-20	V
$V_{GS}$	gate-source voltage			-12	12	V
I <sub>D</sub>	drain current	V <sub>GS</sub> = -4.5 V; T <sub>sp</sub> = 25 °C		-	-18	Α
		V <sub>GS</sub> = -4.5 V; T <sub>sp</sub> = 100 °C		-	-11	Α
		V <sub>GS</sub> = -4.5 V; T <sub>amb</sub> = 25 °C	[1]	-	-6	Α
I <sub>DM</sub>	peak drain current	$T_{sp}$ = 25 °C; single pulse; $t_p \le 10 \mu s$		-	-72	Α
P <sub>tot</sub>	total power dissipation	T <sub>sp</sub> = 25 °C		-	19	W
		T <sub>amb</sub> = 25 °C	[1]	-	2	W
Tj	junction temperature			-55	175	°C
T <sub>amb</sub>	ambient temperature			-55	175	°C
T <sub>stg</sub>	storage temperature			-65	175	°C
Source-drain d	iode		'	'		_
Is	source current	T <sub>sp</sub> = 25 °C		-	-19	Α
		T <sub>amb</sub> = 25 °C	[1]	-	-2	Α
I <sub>SM</sub>	peak source current	single pulse; $t_p \le 10 \mu s$ ; $T_{sp} = 25 °C$		-	-75	Α
ESD maximum	rating					
V <sub>ESD</sub>	electrostatic discharge voltage	НВМ	[2]	-	1000	V
Avalanche ruge	gedness			'		•
E <sub>DS(AL)S</sub>	non-repetitive drain- source avalanche energy	T <sub>j(init)</sub> = 25 °C; I <sub>D</sub> = 1.5 A; DUT in avalanche (unclamped)		-	15	mJ

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.
- [2] Measured between all pins.

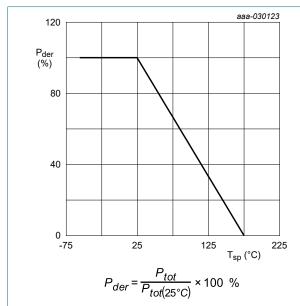


Fig. 1. Normalized total power dissipation as a function of solder point temperature

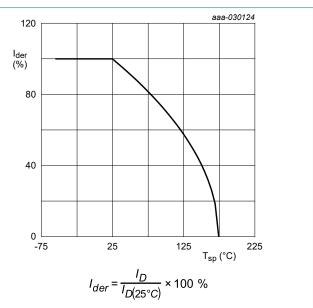


Fig. 2. Normalized continuous drain current as a function of solder point temperature

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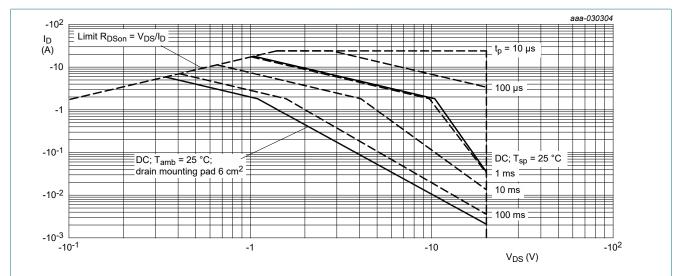


Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

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## 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	66	76	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	4	8	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.

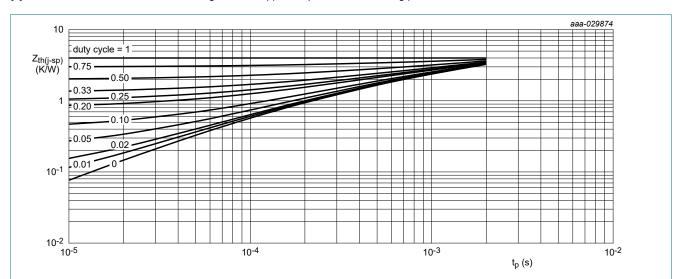


Fig. 4. Transient thermal impedance from junction to solder point as a function of pulse duration; typical values

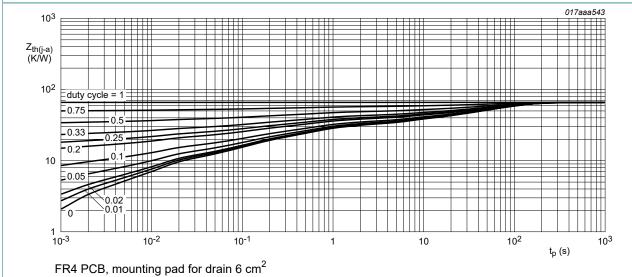


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

# 10. Characteristics

#### **Table 7. Characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static char	acteristics					
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	$I_D$ = -250 $\mu$ A; $V_{GS}$ = 0 V; $T_j$ = 25 °C	-20	-	-	V
$V_{GSth}$	gate-source threshold voltage	$I_D = -250 \mu A; V_{DS} = V_{GS}; T_j = 25 °C$	-0.6	-0.95	-1.3	V
I <sub>DSS</sub>	drain leakage current	$V_{DS} = -20 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ °C}$	-	-	-1	μΑ
		V <sub>DS</sub> = -20 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 125 °C	-	-	-20	μΑ
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = -12 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	-10	μΑ
		V <sub>GS</sub> = 12 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	10	μA
		$V_{GS} = -4.5 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C}$	-	-	-2	μA
		V <sub>GS</sub> = 4.5 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	2	μΑ
R <sub>DSon</sub>	drain-source on-state	$V_{GS} = -8 \text{ V}; I_D = -6 \text{ A}; T_j = 25 ^{\circ}\text{C}$	-	26	33	mΩ
	resistance	V <sub>GS</sub> = -8 V; I <sub>D</sub> = -6 A; T <sub>j</sub> = 175 °C	-	40	50	mΩ
		$V_{GS}$ = -4.5 V; $I_D$ = -6 A; $T_j$ = 25 °C	-	30	38	mΩ
		$V_{GS}$ = -2.5 V; $I_D$ = -2 A; $T_j$ = 25 °C	-	46	64	mΩ
9 <sub>fs</sub>	forward transconductance	$V_{DS} = -10 \text{ V}; I_D = -6 \text{ A}; T_j = 25 \text{ °C}$	-	20	-	S
$R_G$	gate resistance	f = 1 MHz	-	21	-	Ω
Dynamic c	haracteristics					
Q <sub>G(tot)</sub>	total gate charge	$V_{DS}$ = -10 V; $I_{D}$ = -5.8 A; $V_{GS}$ = -4.5 V;	-	10.6	16	nC
Q <sub>GS</sub>	gate-source charge	T <sub>j</sub> = 25 °C	-	2.1	-	nC
Q <sub>GD</sub>	gate-drain charge		-	3.6	-	nC
C <sub>iss</sub>	input capacitance	V <sub>DS</sub> = -10 V; f = 1 MHz; V <sub>GS</sub> = 0 V;	-	1025	-	pF
C <sub>oss</sub>	output capacitance	T <sub>j</sub> = 25 °C	-	137	-	pF
C <sub>rss</sub>	reverse transfer capacitance		-	113	-	pF
t <sub>d(on)</sub>	turn-on delay time	$V_{DS} = -10 \text{ V}; I_D = -5.8 \text{ A}; V_{GS} = -4.5 \text{ V};$	-	6	-	ns
t <sub>r</sub>	rise time	$R_{G(ext)} = 6 \Omega; T_j = 25 °C$	-	17	-	ns
t <sub>d(off)</sub>	turn-off delay time		-	23	-	ns
t <sub>f</sub>	fall time		-	19	-	ns
Source-dra	ain diode					
$V_{SD}$	source-drain voltage	$I_S = -2 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C}$	-	-0.8	-1.2	V
t <sub>rr</sub>	reverse recovery time	$I_S = -2 \text{ A}; dI_S/dt = 100 \text{ A/}\mu\text{s}; V_{GS} = 0 \text{ V};$	-	17	-	ns
Q <sub>r</sub>	recovered charge	V <sub>DS</sub> = -10 V; T <sub>i</sub> = 25 °C		5		nC

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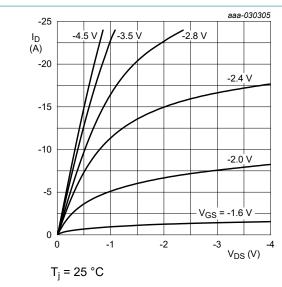


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

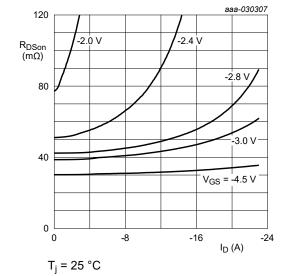


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

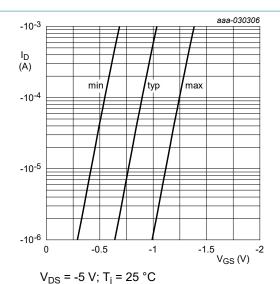


Fig. 7. Sub-threshold drain current as a function of

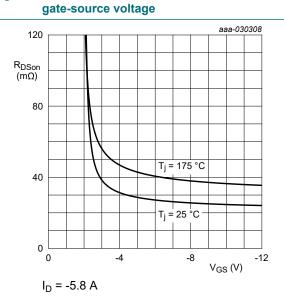


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

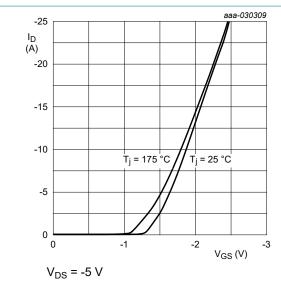


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

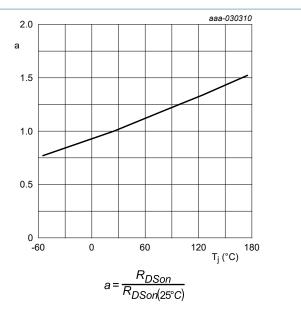


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

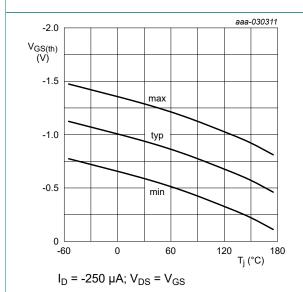


Fig. 12. Gate-source threshold voltage as a function of junction temperature

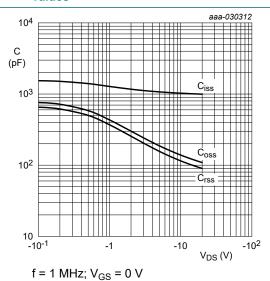


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

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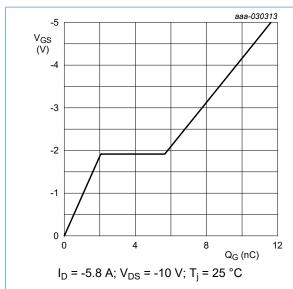


Fig. 14. Gate-source voltage as a function of gate charge; typical values

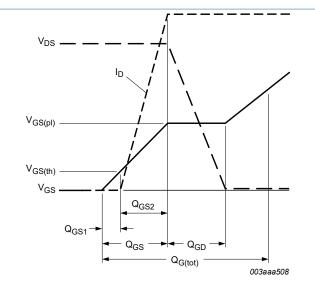


Fig. 15. Gate charge waveform definitions

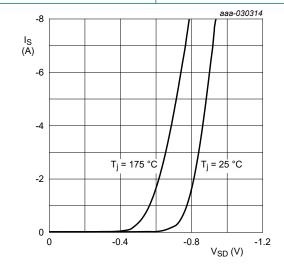
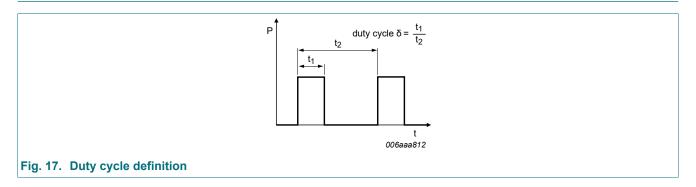


Fig. 16. Source current as a function of source-drain voltage; typical values

 $V_{GS} = 0 V$ 

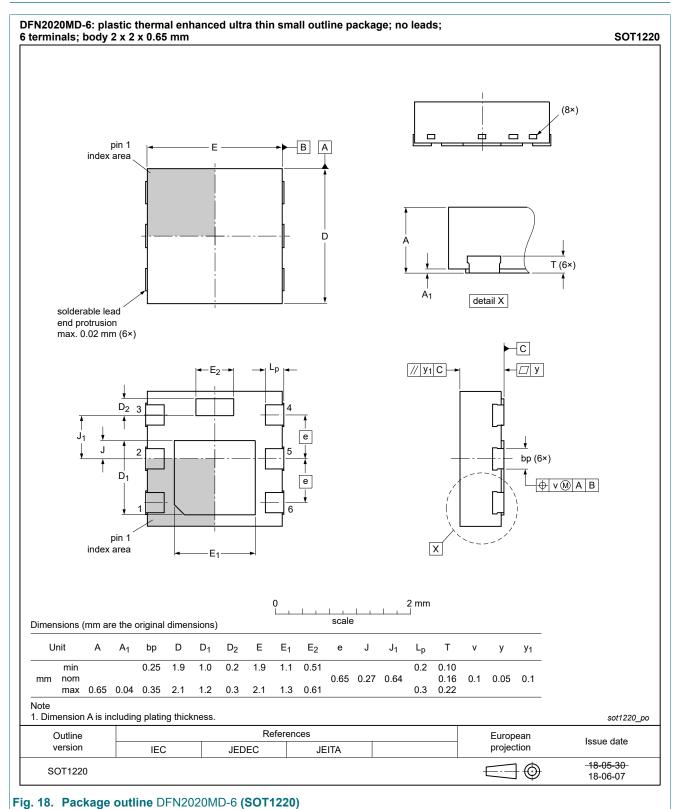
## 11. Test information



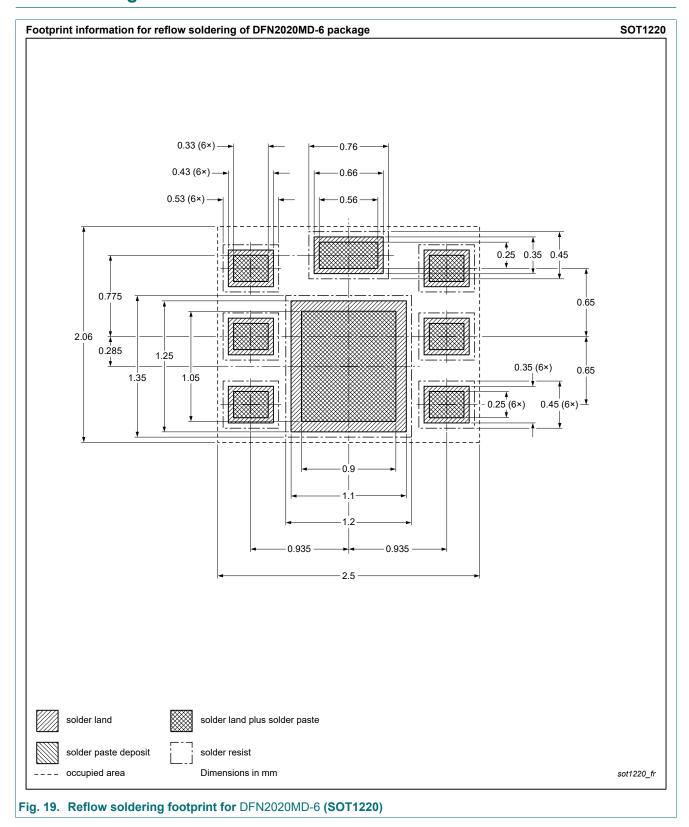
### **Quality information**

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

# 12. Package outline



# 13. Soldering



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20 V, P-channel Trench MOSFET

# 14. Revision history

#### **Table 8. Revision history**

- and the state of								
Data sheet ID	Release date	Data sheet status	Change notice	Supersedes				
BUK4D38-20P v.3	20200709	Product data sheet	-	BUK4D38-20P v.2				
Modifications:	Product status chang	Product status changed.						
BUK4D38-20P v.2	20200121	Objective data sheet	-	BUK4D38-20P v.1				
BUK4D38-20P v.1	20191025	Objective data sheet	-	-				

## 15. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- Please consult the most recently issued document before initiating or completing a design.
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